

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Donjiang WANG</td> <td>09/17/2012</td> </tr> <tr> <td>Steven ZHANG</td> <td>09/17/2012</td> </tr> </tbody> </table>		Name	Execution Date	Donjiang WANG	09/17/2012	Steven ZHANG	09/17/2012						
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>Semiconductor Manufacturing International (Shanghai) Corporation</td> </tr> <tr> <td>Street Address:</td> <td>18 Zhangjiang Road, Pudong New Area</td> </tr> <tr> <td>City:</td> <td>SHANGHAI</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>201203</td> </tr> </table>		Name:	Semiconductor Manufacturing International (Shanghai) Corporation	Street Address:	18 Zhangjiang Road, Pudong New Area	City:	SHANGHAI	State/Country:	CHINA	Postal Code:	201203		
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<table border="1"> <tr> <td>Name:</td> <td>Semiconductor Manufacturing International (Beijing) Corporation</td> </tr> <tr> <td>Street Address:</td> <td>18 Wenchang Road</td> </tr> <tr> <td>Internal Address:</td> <td>Beijing Economic-Technological Development Area</td> </tr> <tr> <td>City:</td> <td>BEIJING</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>100176</td> </tr> </table>		Name:	Semiconductor Manufacturing International (Beijing) Corporation	Street Address:	18 Wenchang Road	Internal Address:	Beijing Economic-Technological Development Area	City:	BEIJING	State/Country:	CHINA	Postal Code:	100176
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PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13660853</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13660853								
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CORRESPONDENCE DATA													
Fax Number:	4087258263												
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ATTORNEY DOCKET NUMBER:

SMIC00008 US

NAME OF SUBMITTER:

Gideon Gimlan, Reg. No. 31,955

Total Attachments: 5

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Attorney Docket No.: SMIC00008 US

SMIC No:2011-00500-SH-US

**ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, we

Donjiang Wang of 18# Zhangjiang Road, Pudong New Area  
Shanghai, P.R.C.

Steven Zhang of 18# Zhangjiang Road, Pudong New Area  
Shanghai, P.R.C.

hereby sell, assign and transfer to **Semiconductor  
Manufacturing International Corporation**, having a place of business at 18 Zhangjiang  
Road, Pudong New Area, Shanghai, P.R.C. 201203 and at 18 Wenchang Road, Beijing  
Economic-Technological Development Area, Beijing, China, 100176, its successors and  
assigns, the entire right, title and interest throughout the world in our invention in

**METHOD OF FABRICATING MINIATURIZED SEMICONDUCTOR OR OTHER  
DEVICE**


for which we have executed a United States patent application on or about the date of this  
assignment, and all patent applications and patents of every country for said invention,  
including divisions, reissues, continuations and extensions thereof, and all rights of priority  
resulting from the filing of said applications; we authorize the above-named assignee to apply  
for patents of foreign countries for said invention, and to claim all rights of priority without  
further authorization from us; we agree to execute all papers useful in connection with said  
United States and foreign applications, and generally to do everything possible to aid said  
assignee, its successors, assigns and nominees, at their request and expense, in obtaining and  
enforcing patents for said invention in all countries; and we request that the United States  
Patent and Trademark Office issue all patents granted for said invention to the above-named  
assignee, its successors and assigns.

Executed this 17 day of 09, 2012.

Donjiang Wang  
Donjiang Wang

WITNESSED: 王岐堂  
Signature  
王岐堂  
Date  
2012-9-17  
Type or print name of witness

Executed this 17 day of 09, 2012.

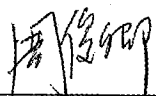
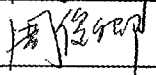
  
\_\_\_\_\_  
Steven Zhang

WITNESSED:

Signature

Date

Type or print name of witness

  
  
2012-9-17

**DECLARATION FOR PATENT APPLICATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below adjacent to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of subject matter (process, machine, manufacture, or composition of matter, or an improvement thereof) which is claimed and for which a patent is sought by way of the application entitled

**METHOD OF FABRICATING MINIATURIZED SEMICONDUCTOR OR OTHER DEVICE**

which (check)  is attached hereto.  
 and is amended by the Preliminary Amendment attached hereto.  
 was filed on \_\_\_\_\_ as Application Serial No.  
 and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
Number	Country	Day/Month/Year Filed	Yes	No
201110335055.4	CN	10/28/2011	<input checked="" type="checkbox"/>	<input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

Provisional Application Number	Filing Date

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or PCT international application(s) designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information, which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)

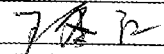
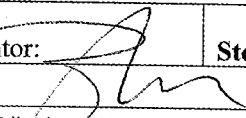
I hereby appoint the following practitioners to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith:

**Kieun "Jenny" Sung**  
**Customer No. 90323**

Please address all correspondence and telephone calls to:

**Kieun "Jenny" Sung**  
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 Cupertino, CA 95014  
 Telephone: 408-331-1670  
 Facsimile: 408-752-8263

I declare that all statements made herein of my own knowledge are true, all statements made herein on information and belief are believed to be true, and all statements made herein are made with the knowledge that whoever, in any matter within the jurisdiction of the Patent and Trademark Office, knowingly and willfully falsifies, conceals, or covers up by any trick, scheme, or device a material fact, or makes any false, fictitious or fraudulent statements or representations, or makes or uses any false writing or document knowing the same to contain any false, fictitious or fraudulent statement or entry, shall be subject to the penalties including fine or imprisonment or both as set forth under 18 U.S.C. 1001, and that violations of this paragraph may jeopardize the validity of the application or this document, or the validity or enforceability of any patent, trademark registration, or certificate resulting therefrom.

Full name of first inventor:		Donjiang Wang	
Inventor's Signature:		Date:	2012-9-17
Residence:	18# Zhangjiang Road, Pudong New Area Shanghai, P.R.C.		
Post Office Address:	18# Zhangjiang Road, Pudong New Area Shanghai, P.R.C.		Citizenship: China
Full name of second inventor:		Steven Zhang	
Inventor's Signature:		Date:	2012-9-17
Residence:	18# Zhangjiang Road, Pudong New Area Shanghai, P.R.C.		
Post Office Address:	18# Zhangjiang Road, Pudong New Area Shanghai, P.R.C.		Citizenship: China

Attorney Docket No. SMIC00008 US

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